TITLE: SPECIFICATION CONTROL DRAWING

PART IDENTIFIER: SMT3737F

DESCRIPTION: SURFACE MOUNT TERMINATION, BERYLLIA, LEAD FREE PLATING.

ASSEMBLY DWG: 1101954

1.0 SPECIFICATIONS:

- 1.1 ELECTRICAL:
 - 1.1.1 IMPEDANCE: 50Ω NOMINAL.
 - 1.1.2 FREQUENCY: DC 2 GHZ.
 - 1.1.3 VSWR: 1.35:1 MAX.
 - 1.1.4 INPUT POWER:
 - 1.1.4.1 150 WATTS. CHIP SOLDERED TO MOUNTING SURFACE. MOUNTING SURFACE TEMPERATURE MAINTAINED AT 100 °C MAXIMUM. APPLY LINEAR DE-RATING OF INPUT POWER TO 0 WATTS AT 150 °C.
- 1.2 MECHANICAL:
 - 1.2.1 OUTLINE DWG: SEE SHEET 2.
 - 1.2.2 WORKMANSHIP: PER MIL-PRF-55342
 - 1.2.3 THERMAL IMPEDANCE (R_O)
 - 1.2.3.1 0.333 $^{\circ}$ C / WATT R $_{\odot}$ FROM RESIST FILM TO MOUNTING SURFACE DIRECTLY UNDER CENTER OF CHIP. CHIP SOLDERED DIRECTLY TO MOUNTING SURFACE.
 - 1.2.4 FILM TEMPERATURE (T_F)
 - 1.2.4.1 200 °C ABSOLUTE MAXIMUM FILM TEMPERATURE. DE-RATE TO 150 °C MAXIMUM FILM TEMPERATURE FOR ALL MILITARY/HIGH-RELIABILITY APPLICATIONS.
 - 1.2.5 THERMAL
 - 1.2.5.1 DETERMINE MAXIMUM MOUNTING SURFACE TEMPERATURE BY APPLYING THE FOLLOWING FORMULA: $T_S = T_F (P_{MAX} X R_{\Theta})$

WHERE: T_S = MAXIMUM MOUNTING SURFACE TEMPERATURE

 T_F = MAXIMUM FILM TEMPERATURE P_{MAX} = MAXIMUM APPLIED INPUT POWER R_{\odot} = CHIP THERMAL IMPEDANCE.

- 1.3 ENVIRONMENTAL:
 - 1.3.1 TEMPERATURE RANGE:

1.3.1.1 NON-OPERATING: -55 °C TO +150 °C. 1.3.1.2 OPERATING: -55 °C TO +150 °C.

- 2.0 UNIT MARKING: NONE.
- 3.0 QUALITY ASSURANCE:
 - 3.1 SAMPLE INSPECT PER ANSI/ASQC Z1.4 GENERAL INSPECTION, LEVEL II, AQL = 1.0.
 - 3.1.1 VISUAL AND MECHANICAL PER 824W154.
 - 3.1.2 DC RESISTANCE: $50\Omega \pm 5\%$.
 - 3.2 DATA REQUIREMENTS:
 - 3.2.1 NO TEST DATA REQUIRED FOR CUSTOMER.
 - 3.2.2 DATA RETENTION 24 MONTHS.
- 4.0 PACKAGING: STANDARD PACKING PER 755W002.

EMC TECHNOLOGY	CAGE CODE # 24602		DWG#	1010485000		
8851 SW OLD KANSAS AVE.	CHANGE NOTICE	EN 08-E0615	REV LVL	Α		
STUART, FL 34997			SHEET	1	OF	2

